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## Changes in GMLRH-25

### RF

#### PWB Layout changes:

- 100 ohm resistor (R310) added to RFCIk line to improve EMI blocking.
- Removed through-hole via on RFCIk line and replaced with blind and buried vias (signal routing was not changed).
- R350 and C361 moved slightly (~0.1mm) to allow greater tolerance between components and light guide.
- Display connector (X302) pads increased in length and micro-vias added to improve pad to laminate strength and reduce probability of pads peeling off due to mechanical drop.
- Via in vibra pad moved slightly to improve spring contact reliability.
- Vias in HP speaker pads moved slightly to improve spring contact reliability.
- Opening in IHF speaker pad solder mask increased to improve contact reliability.

Removed decoupling capacitors C130, 131, 132 and 200 for improved display performance.

Change D400 version of UPP from UPP8Mv2.2, v2.40 & v2.41 (4370873) to UPP8Mv2.6 & v2.10 (4370931) or UPP8Mv2.2, v2.40 & v2.41 (4370873). Form and function of both parts is the same.

### BB

No Changes

## Results of internal review (FCC focus)

FCC tests: Field Strength of Spurious Radiation  
SAR tests not required